 **EPOXY ADHESIVE**

**EPOXY 021906-1T**

**HIGH THERMAL K EPOXY ENCAPSULANT**

**TECHNICAL DATA**

**Product Description**

Epoxy 021906-1T is a room temperature curing two part epoxy system designed to be used to encapsulate electronic packages. This product has been formulated so as to provide the user with an easy to work with one to one by volume mix ratio. Once encapsulated with the Epoxy 021906-1T an electronic package will exhibit a higher resistance to both physical shock as well as exposure to water and other potentially harmful chemicals.

**APPLICATIONS**

**FEATURES**

**RECOMMENDED SUBSTRATES**

* Electronic encapsulation
* Two part convenient mix ratio
* Room temperature cure
* Moisture resistant
* Chemical resistant
* Physical shock resistant

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| **UNCURED PROPERTIES** |
| **Property** | **Value** | **Test Method** |
| Solvent Content | No Nonreactive Solvents | N/A |
| Chemical Class, PT A:B | Epoxy : Amine | N/A |
| Color, PT A:B | Black : Tan | N/A |
| Viscosity, PT A @ 25C, cps | 16,500 to 50,000 | QPTEST001 |
| Viscosity, PT B @ 25C, cps | 20,000 to 36,000 | QPTEST001 |
| Specific Gravity, PT A | 2.34 | QPTEST002 |
| Specific Gravity, PT B | 1.57 | QPTEST002 |
| Filler Base | Tabular Alumina | N/A |

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| **CURED MECHANICAL PROPERTIES** |
| **Property** | **Value** | **Test Method** |
| Durometer Hardness, Shore D | 55 to 65 | QPTEST012 |
| Moisture Resistance | Excellent | N/A |
| CTE, C, -40 to 80C, ppm | 38 | N/A |
| Peak Intermittent Temperature, C | 180 | N/A |
| Thermal Conductivity, BTU in/hr-ft^2, F | 9 | N/A |
| Thermal Conductivity, W/Meter, K | 1.29 | N/A |
| Glass Transition Temperature (Tg), C | 31.45 | N/A |
| Comparative Tracking Index, volts | >175 | N/A |
| Dielectric Strength, Volt/mil | >500 | N/A |
| Dissipation Factor, 1MHz | 0.0024 | QPTEST011 |
| Operational Temperature Range, C | -50 to 155 | N/A |

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| **CURE OVERVIEW** |
| **Property** | **Value** | **Test Method** |
| Mix ratio by Volume, PT A:B | 1:1 | N/A |
| Work Life @ RT, min | 60 | N/A |
| Gel Time @ RT, min, 100g | 198 | QPTEST020 |
| Cure Time @ RT, hr | 24 to 48 | N/A |
| Cure Time @ 65C, min | 120 | N/A |

# Storage:

Store material in cool, dry location at a temperature between 10°C to 28°C. Keep from freezing. Refer to packaging specific quote for shelf life information. Consult SDS for safe handling recommendations.

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